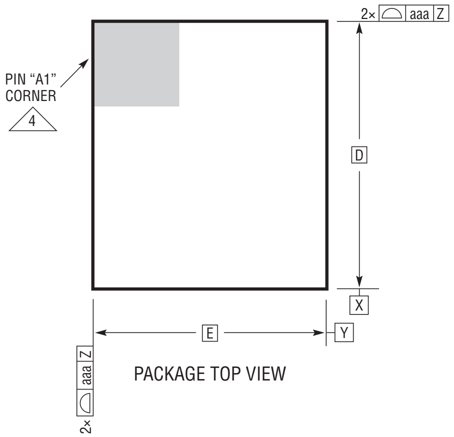
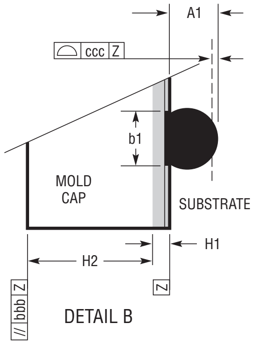
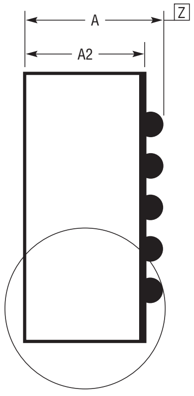
BGA Package
25-Lead (4mm × 3.5mm × 1.8mm)
(Reference LTC DWG# 05-08-1627 Rev Ø)



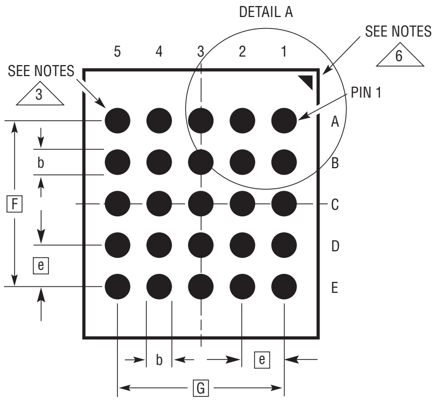
PACKAGE TOP VIEW



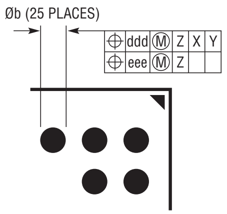
DETAIL B



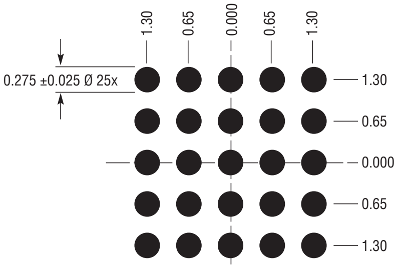
DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



DETAIL A



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS

SYMBOL	MIN	NOM	MAX	NOTES
A	1.63	1.80	1.97	
A1	0.16	0.23	0.30	BALL HT
A2	1.47	1.57	1.67	
b	0.25	0.30	0.35	BALL DIMENSION
b1	0.25	0.28	0.31	PAD DIMENSION
D		4.00		
E		3.50		
e		0.50		
F		2.60		
G		2.60		
H1		0.47 REF		SUBSTRATE THK
H2		1.10 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.08	
ddd			0.15	
eee			0.05	

TOTAL NUMBER OF BALLS: 25

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

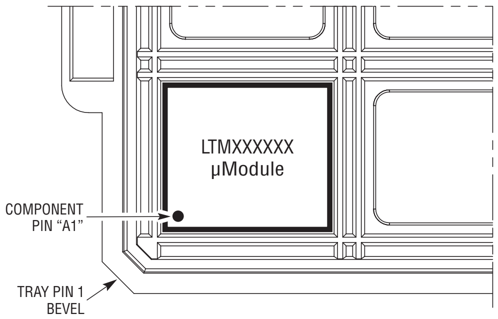
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION